

	Hits	Search Text	DBs
1	3143	156/247,344,584.ccls. or 29/762,426.5426.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
2	4237	156/247,344,584.ccls. or 29/762,426.1,426.5.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
3	1199819	fluid	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
4	517	(156/247,344,584.ccls. or 29/762,426.1,426.5.ccls.) and fluid	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

	Document ID	Issue Date	Pages	Title	Current OR
1	US 20020088558 A1	20020711	43	Method and apparatus for separating composite member using fluid	156/584
2	US 20020053394 A1	20020509	8	Automatic separator and method to obtain circuits for microelectronics	156/249
3	US 6475323 B1	20021105	40	Method and apparatus for separating composite member using fluid	156/239
4	US 5344521 A	19940906	25	Coating film separating device and coating film separation method using the device	156/584
5	US 5110393 A	19920505	13	Method of peeling a bonded film from a circuit board	156/344